



PMEG4015EPK

40 V, 1.5 A low VF MEGA Schottky barrier rectifier

Rev. 2 — 6 March 2012

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small SOD1608 (DFN1608D-2) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- Average forward current: $I_{F(AV)} \leq 1.5$ A
- Reverse voltage: $V_R \leq 40$ V
- Low forward voltage $V_F \leq 610$ mV
- Low reverse current
- AEC-Q101 qualified
- Solderable side pads
- Package height typ. 0.37 mm
- Ultra small and leadless SMD plastic package

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- LED backlight for mobile application
- Low power consumption applications
- Ultra high-speed switching
- Reverse polarity protection

1.4 Quick reference data

Table 1. Quick reference data

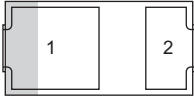

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------|-------------------------|---|-----|-----|-----|---------|
| $I_{F(AV)}$ | average forward current | $\delta = 0.5$; $f = 20$ kHz; $T_{amb} \leq 65$ °C; [1] square wave | - | - | 1.5 | A |
| | | $\delta = 0.5$; $f = 20$ kHz; $T_{sp} \leq 135$ °C; square wave | - | - | 1.5 | A |
| V_R | reverse voltage | $T_j = 25$ °C | - | - | 40 | V |
| V_F | forward voltage | $I_F = 1.5$ A; pulsed; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_j = 25$ °C | - | 540 | 610 | mV |
| I_R | reverse current | $V_R = 10$ V; $T_j = 25$ °C | - | 1 | 5 | μ A |
| t_{rr} | reverse recovery time | $I_R = 0.5$ A; $I_F = 0.5$ A; $I_{R(meas)} = 0.1$ A; $T_j = 25$ °C | - | 4 | - | ns |

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.



2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|------------------------|---|--|
| 1 | K | cathode ^[1] |  |  <i>sym001</i> |
| 2 | A | anode | | |

Transparent top view

SOD1608 (DFN1608D-2)

[1] The marking bar indicates the cathode.

3. Ordering information

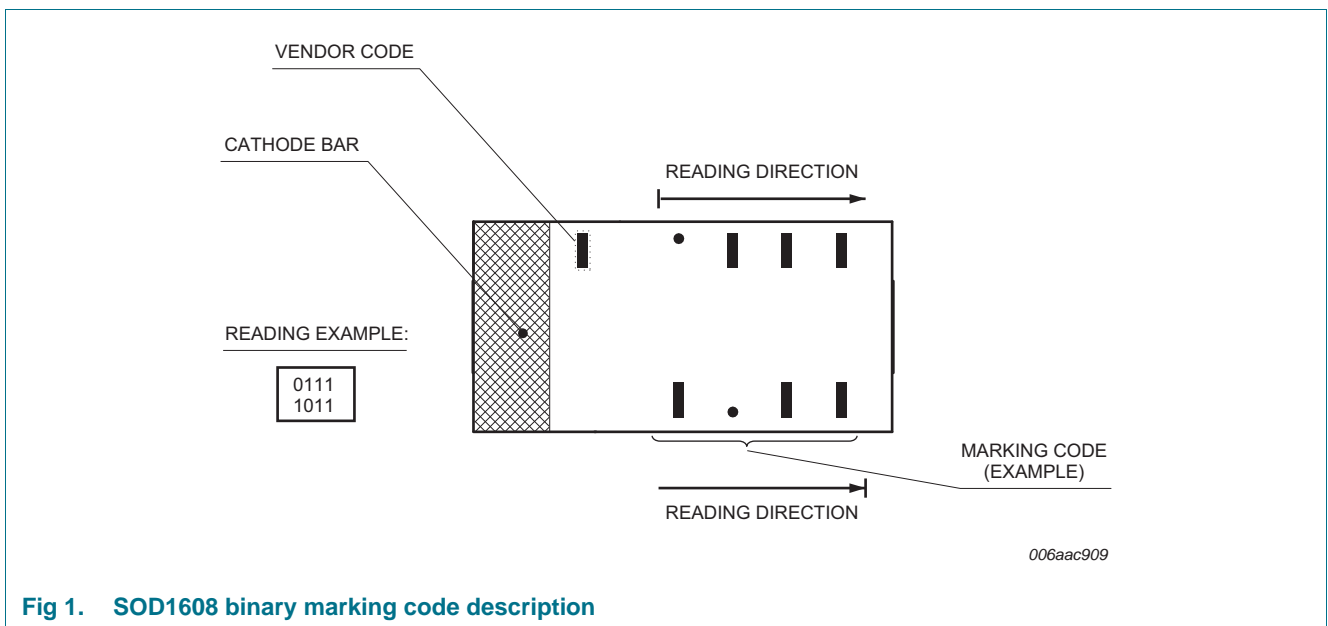
Table 3. Ordering information

| Type number | Package | | |
|-------------|------------|---|---------|
| | Name | Description | Version |
| PMEG4015EPK | DFN1608D-2 | Leadless ultra small plastic package; 2 terminals | SOD1608 |

4. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMEG4015EPK | 0110 0000 |



5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-------------|-------------------------------------|--|--------|------|------|
| V_R | reverse voltage | $T_j = 25\text{ °C}$ | - | 40 | V |
| I_F | forward current | $T_{sp} \leq 130\text{ °C}$ | - | 2.1 | A |
| $I_{F(AV)}$ | average forward current | $\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{amb} \leq 65\text{ °C}$ | [1] | 1.5 | A |
| | | $\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 135\text{ °C}$ | - | 1.5 | A |
| I_{FRM} | repetitive peak forward current | $t_p \leq 1\text{ ms}$; $\delta \leq 0.25$ | - | 4 | A |
| I_{FSM} | non-repetitive peak forward current | $t_p = 8\text{ ms}$; $T_{j(Init)} = 25\text{ °C}$; square wave | - | 5 | A |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | [2][3] | 415 | mW |
| | | | [4][3] | 895 | mW |
| | | | [1][3] | 1565 | mW |
| T_j | junction temperature | | - | 150 | °C |
| T_{amb} | ambient temperature | | -55 | 150 | °C |
| T_{stg} | storage temperature | | -65 | 150 | °C |

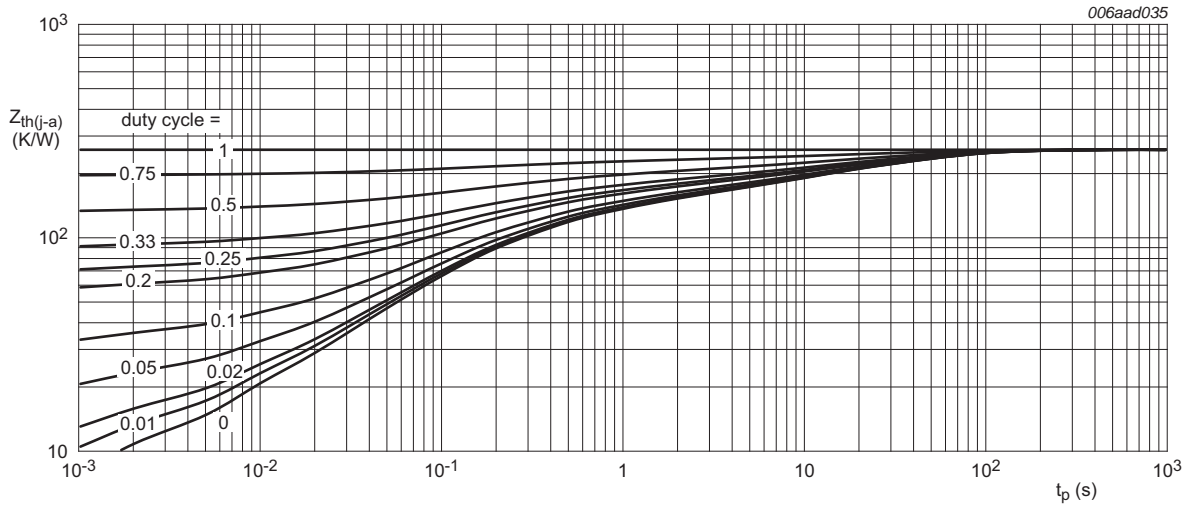
- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
 [3] Reflow soldering is the only recommended soldering method.
 [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

6. Thermal characteristics

Table 6. Thermal characteristics

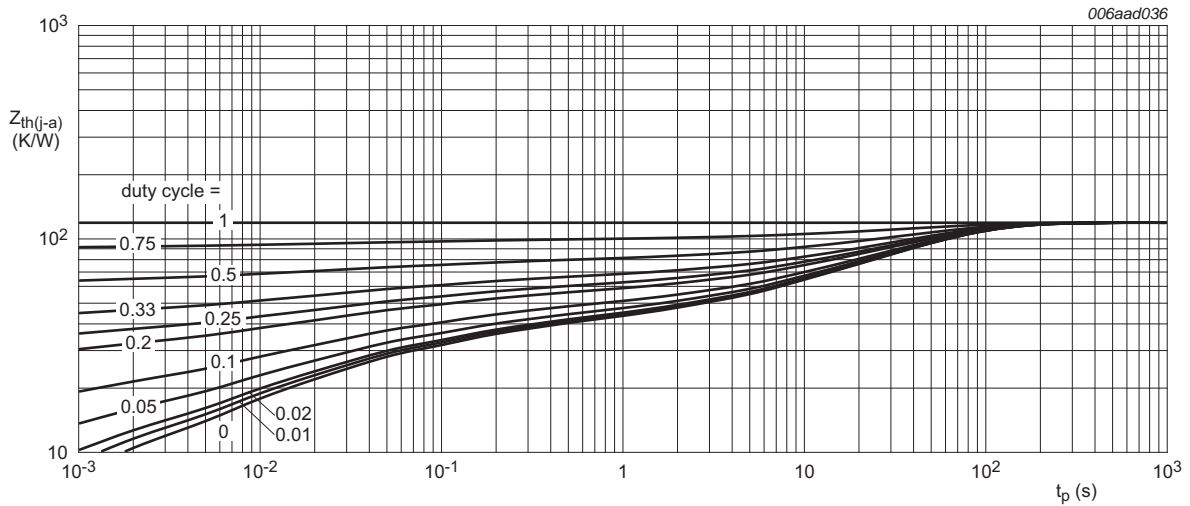
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------------|--|-------------|-----------|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1][2][3] | - | 300 | K/W |
| | | | [1][4][3] | - | 140 | K/W |
| | | | [1][5][3] | - | 80 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | [6] | - | 20 | K/W |

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
 [3] Reflow soldering is the only recommended soldering method.
 [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
 [5] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.
 [6] Soldering point of cathode tab.



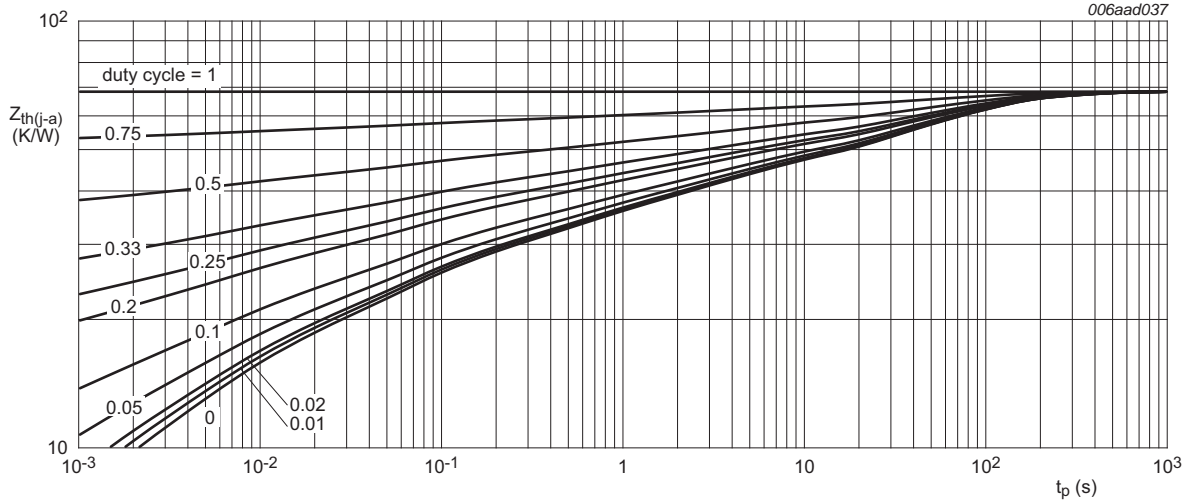
FR4 PCB, standard footprint

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



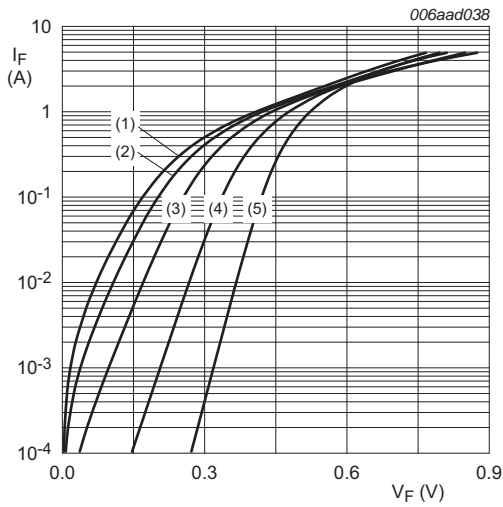
Ceramic PCB, Al₂O₃, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

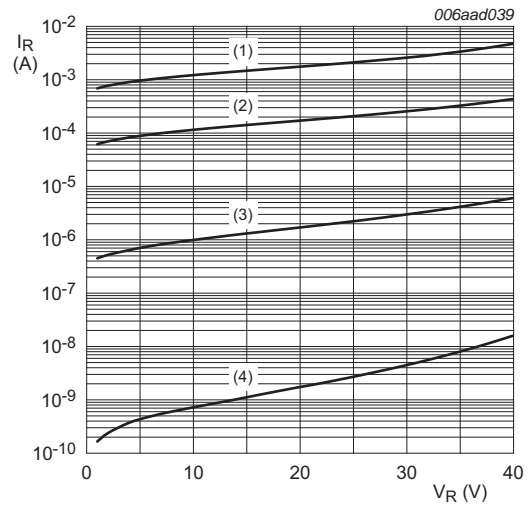
Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|-------------------------------|--|-----|-----|-----|------|
| V _F | forward voltage | I _F = 100 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C | - | 330 | 380 | mV |
| | | I _F = 500 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C | - | 415 | 480 | mV |
| | | I _F = 1 A; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C | - | 490 | 550 | mV |
| | | I _F = 1.5 A; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C | - | 540 | 610 | mV |
| I _R | reverse current | V _R = 10 V; T _j = 25 °C | - | 1 | 5 | μA |
| | | V _R = 40 V; T _j = 25 °C | - | 8 | 30 | μA |
| C _d | diode capacitance | V _R = 1 V; f = 1 MHz; T _j = 25 °C | - | 75 | 90 | pF |
| | | V _R = 10 V; f = 1 MHz; T _j = 25 °C | - | 30 | 40 | pF |
| t _{rr} | reverse recovery time | I _F = 0.5 A; I _R = 0.5 A; I _{R(meas)} = 0.1 A; T _j = 25 °C | - | 4 | - | ns |
| V _{FRM} | peak forward recovery voltage | I _F = 0.5 A; dI _F /dt = 20 A/μs; T _j = 25 °C | - | 440 | - | mV |



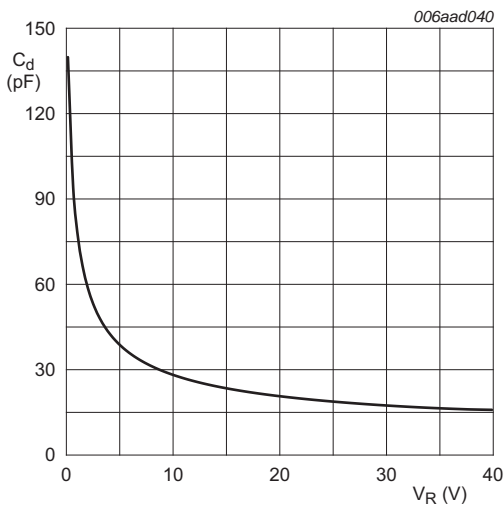
- (1) $T_j = 150\text{ }^\circ\text{C}$
- (2) $T_j = 125\text{ }^\circ\text{C}$
- (3) $T_j = 85\text{ }^\circ\text{C}$
- (4) $T_j = 25\text{ }^\circ\text{C}$
- (5) $T_j = -40\text{ }^\circ\text{C}$

Fig 5. Forward current as a function of forward voltage; typical values



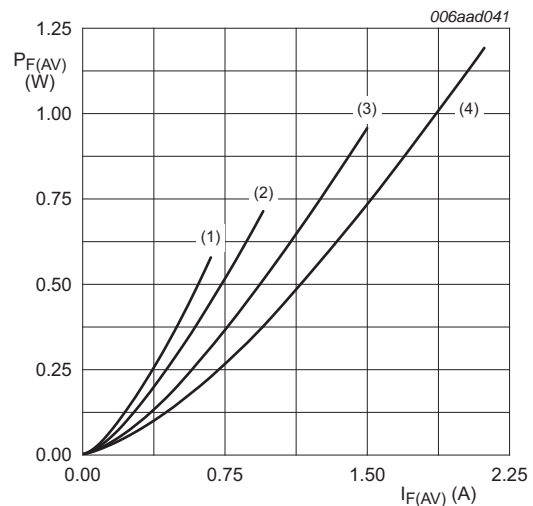
- (1) $T_j = 125\text{ }^\circ\text{C}$
- (2) $T_j = 85\text{ }^\circ\text{C}$
- (3) $T_j = 25\text{ }^\circ\text{C}$
- (4) $T_j = -40\text{ }^\circ\text{C}$

Fig 6. Reverse current as a function of reverse voltage; typical values



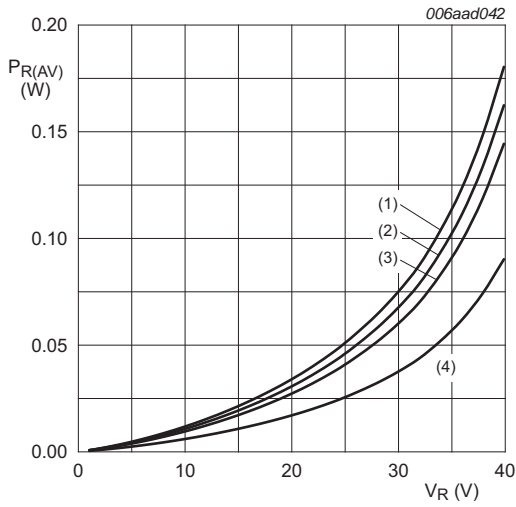
$f = 1\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$

Fig 7. Diode capacitance as a function of reverse voltage; typical values



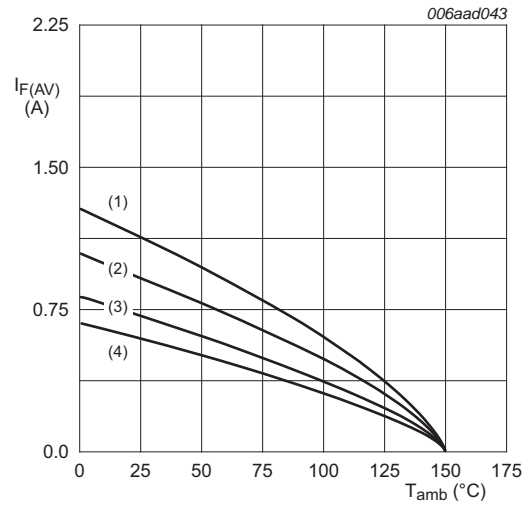
- $T_j = 150\text{ }^\circ\text{C}$
- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

Fig 8. Average forward power dissipation as a function of average forward current; typical values



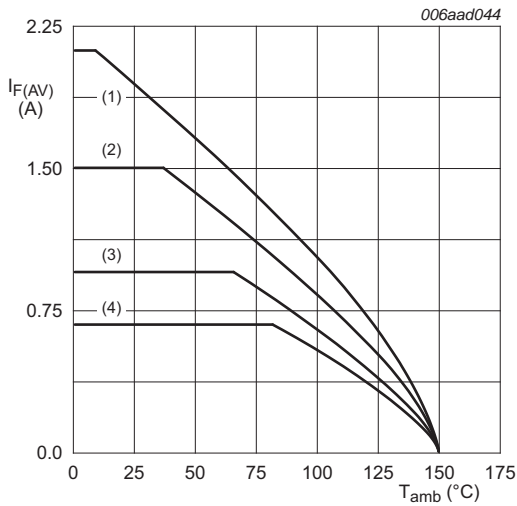
$T_j = 125\text{ °C}$
 (1) $\delta = 1$
 (2) $\delta = 0.9$
 (3) $\delta = 0.8$
 (4) $\delta = 0.5$

Fig 9. Average reverse power dissipation as a function of reverse voltage; typical values



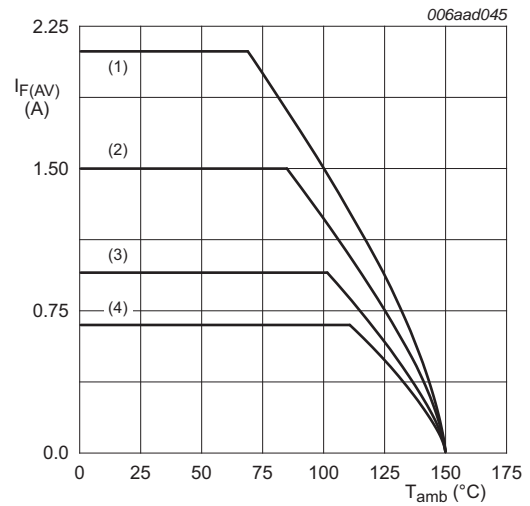
FR4 PCB, standard footprint
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 10. Average forward current as a function of ambient temperature; typical values



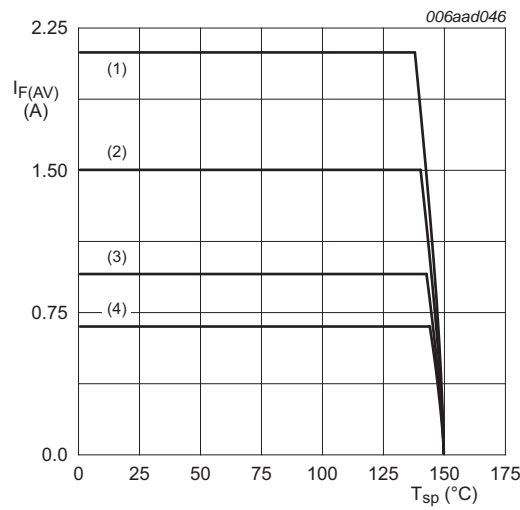
FR4 PCB, mounting pad for cathode 1 cm^2
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3 , standard footprint
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 12. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$

(1) $\delta = 1$ (DC)

(2) $\delta = 0.5$; $f = 20\text{ kHz}$

(3) $\delta = 0.2$; $f = 20\text{ kHz}$

(4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig 13. Average forward current as a function of solder point temperature; typical values

8. Test information

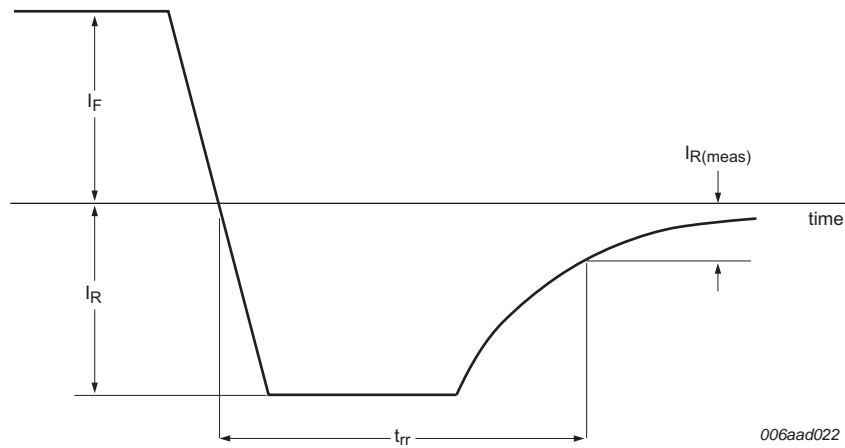


Fig 14. Reverse recovery definition

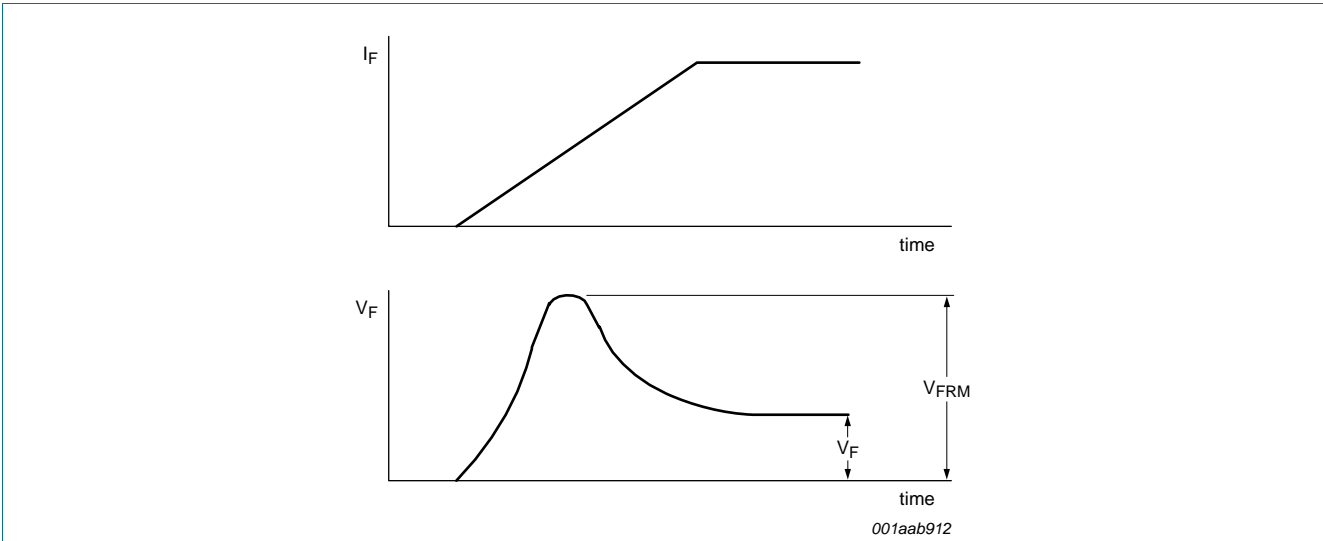


Fig 15. Forward recovery definition

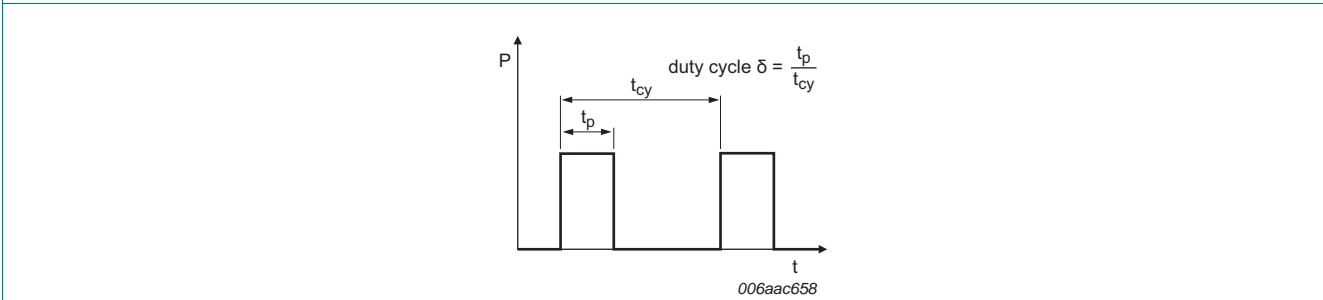


Fig 16. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:
 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

9. Package outline

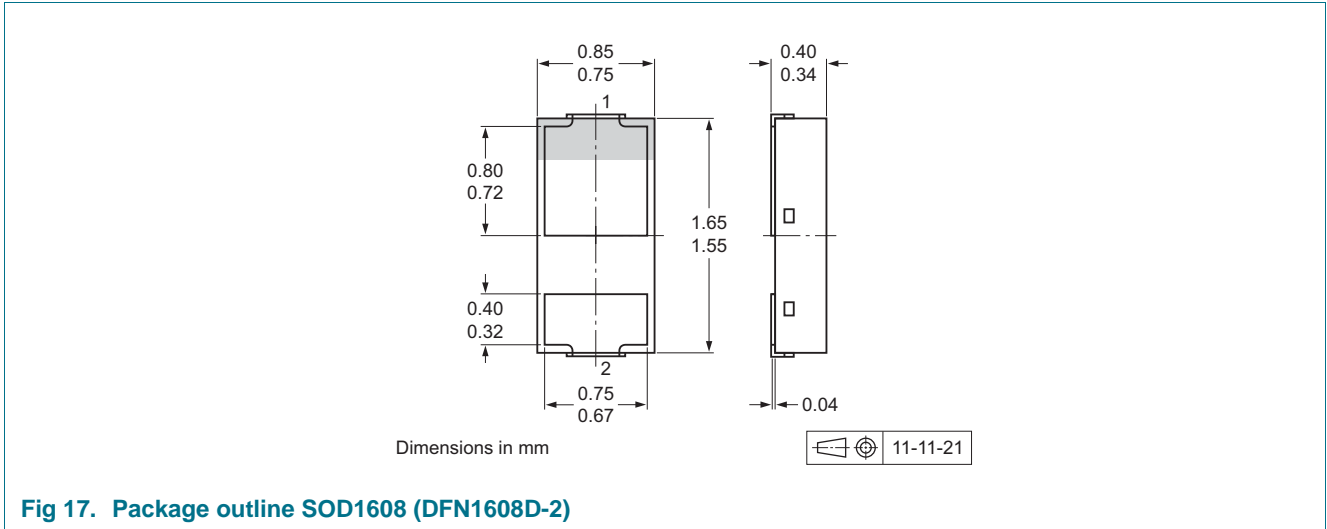


Fig 17. Package outline SOD1608 (DFN1608D-2)

10. Soldering

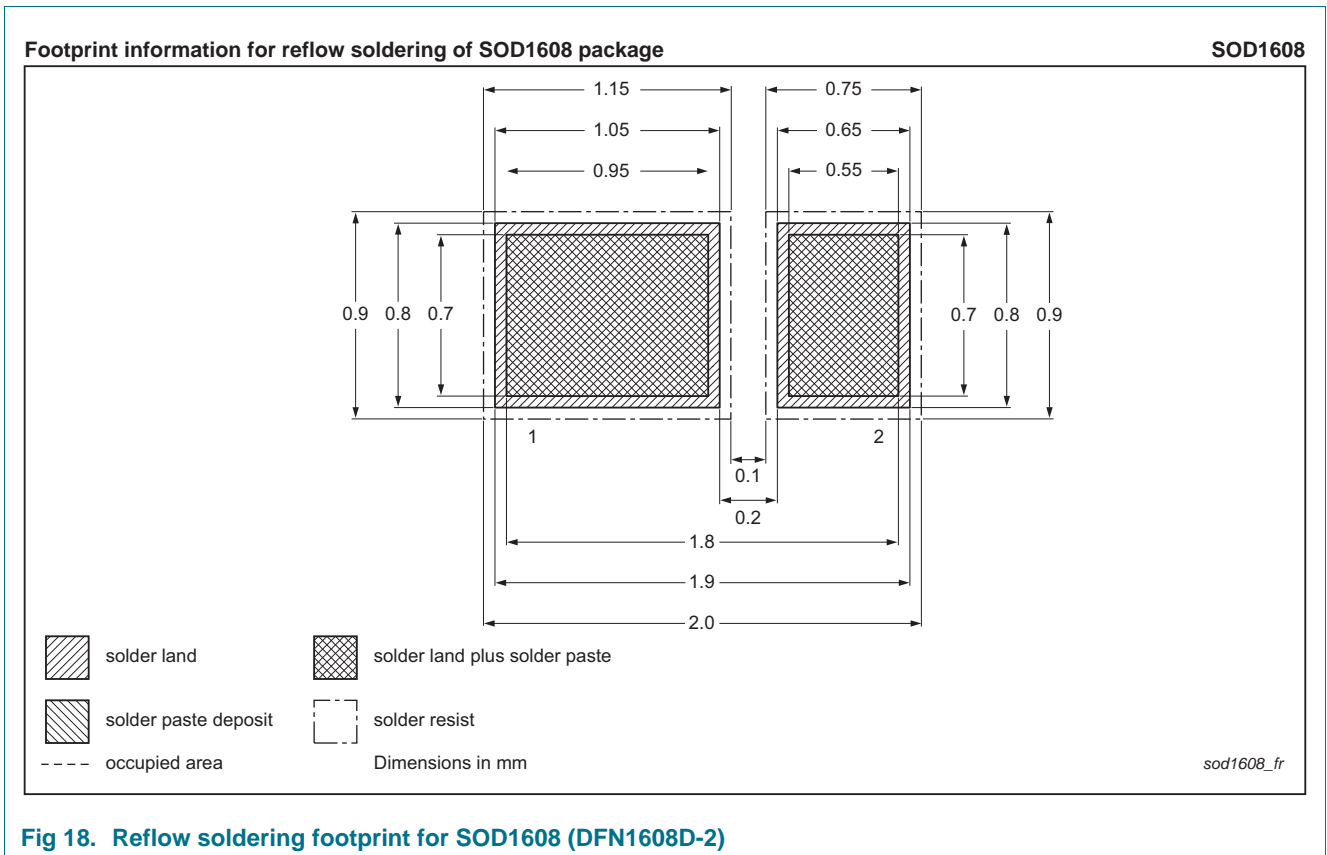


Fig 18. Reflow soldering footprint for SOD1608 (DFN1608D-2)

11. Revision history

Table 8. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-----------------|--|--------------------|---------------|-----------------|
| PMEG4015EPK v.2 | 20120306 | Product data sheet | - | PMEG4015EPK v.1 |
| Modifications: | • Fig 14. and 15 : corrected title | | | |
| PMEG4015EPK v.1 | 20120302 | Product data sheet | - | - |

12. Legal information

12.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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